

SEMI® International MEMS Steering Group – General Meeting



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SEMICON Europa 2004

NA MEMS Standards Activity

- Committee co-chairs:
 - Michael Huff, MEMS Exchange
 - Dan Chilcott, Delphi
 - Win Baylies, BayTech (vice chair)
- Meetings:
 - Austin 15 October
 - La Jolla 15 March

NA MEMS Standards Activity - 2

- Task Forces:

- MEMS Fluidics Interface TF

- Mark Crockett, Applied Materials; Bai Xu, Albany Univ.

- Wafer-bonding Target TF

- Win Baylies, BayTech

- MEMS Test WG

- Dan Chilcott, Delphi; Win Baylies, BayTech

- MEMS Packaging WG

- Charlie Cuneo, Unitek Benchmark

- Process Steps WG

- (no leader at preset)

- Wafer Specifications for MEMS Applications TF

- Graham Fisher, MEMC

NA MEMS Standards Activity - 3

- Wafer Specs for MEMS TF (Silicon Wafer Committee)

- Wafer Survey

- Executed 1Q-2Q03

- Conclusions July 03:

- No CMOS-like single driver for wafer specs

- Several unique segment needs identified

- Report placed on Web [URL, anyone??](#)

- Discussed in Japan, Taiwan, Korea

- SNARFS

- Doc. 3769 Guide for Specifying Wafers for MEMS-Related Bonding Applications

- Doc. 3908 Guide for Specifying Wafers for Direct Bonding Applications

NA MEMS Standards Activity - 4

- Fluidic Interface WG
 - Excellent proposal from Applied Materials
 - SNARF prepared for Guide for Generic Fluidic I/O Design and Fabrication
 - TFOF approved by MEMS Committee
- Wafer-Bond Target TF
 - SNARF for Guide for Specifying On-Wafer Bonding Targets
 - suggested design provided by leading MEMS maker
 - TFOF approved by MEMS Committee
- Substantial discussion in MEMS Committee on standards needed for external data communications to/from MEMS devices
 - Study team established

Europe MEMS Standards Activity

- Committee co-chairs:
 - Viorel Dragoi, EVG
 - Andres Lagos, Colibrys
- Status:
 - 9 meetings, last one in Nijmegen
 - 4 task forces:
 - Wafer Backside Exclusion Frame Size for Wafer Handling
 - Universal Alignment Targets for Wafer Bonding
 - MEMS Terminology
 - MEMS Tray and Carriers (to be confirmed)

Japan MEMS Standards Activity

- Dr. Kuniki Ohwada and Mr. Kazunori Kato will lead Japanese standards activity
 - Dr. Ohwada (ISEL) has much experience in MEMS standardization.
 - A member of IEC SC 47E
 - Mr. Kato (AiT) has contributed to SEMI Standards activities for over 10 years.
 - Division Chair of Test / Packaging Division
 - Committee Chair of Packaging Committee

Japan Standards activity plan

- Plan to hold “MEMS standardization workshop” within 2004
 - Survey of existing MEMS related standards
 - Collect requests for MEMS related standards